



Final Product Change Notification

202305031F01 : SOIC 32LD Exposed Pad Stamped Leadframe Qualification

Note: This notice is NXP Company Proprietary.

Issue Date: May 25, 2023 **Effective date:** Aug 23, 2023

Here is your personalized notification about a NXP general announcement.

Management summary

NXP Semiconductors announces a new stamped leadframe for the SOIC 32 lead exposed pad devices associated with this notification.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

PCN Overview

Description

NXP Semiconductors announces the qualification of a stamped leadframe, replacing the current etched leadframe, for the SOIC 32 lead exposed pad devices associated with this notification. The stamped leadframe products are now qualified for assembly at NXP-ATTJ assembly site, Tianjin China. No change to leadframe base metal material, plating or overall dimensions - except for minor change to exposed pad area shape - but with no impact to exposed pad overall dimensions.

The change from etched to stamped leadframe results in a revision change to the package case outline document 98ASA00259D. The opportunity will be taken to update individual product data sheets to reference the new package drawing, and corresponding Customer Information Notifications will be issued to ensure awareness.

Please see the attached change summary for details, including package exposed pad shape comparison.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-03

Reason

The change from etched to stamped leadframe is required for manufacturing optimization, and supply assurance.

Identification of Affected Products

There is no change to orderable part number or product identification.

Product Availability

Sample Information

Samples are available from May 23, 2023

Production

Planned first shipment Aug 23, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on fit, function, reliability or quality.

Only the form of the leadframe exposed pad area shape changed slightly with the new stamped process, but with no impact to exposed pad overall dimensions.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jun 24, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

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Orderable Part Number#	12NC	Product Type	Product Description
MC33972ATEKR2	935310397518	MC33972ATEKR2	MULT SW DET SUP-WKUP
MCZ33903DS5EKR2	935333189518	MCZ33903DS5EKR2	5V Reg + CAN + 2 LIN
MCZ33903DP5EKR2	935333218518	MCZ33903DP5EKR2	SBC W/HIGH SPEED CAN 5V
MC33972ATEK	935310397574	MC33972ATEK	MULT SW DET SUP-WKUP
MC33975ATEKR2	935311836518	MC33975ATEKR2	ENHANCED MULTI SW DETECT
MC33975TEKR2	935315721518	MC33975TEKR2	MULTI SW DETECT INTERFAC
MC33975ATEK	935311836574	MC33975ATEK	ENHANCED MULTI SW DETECT
MCZ33903DD5EKR2	935333165518	MCZ33903DD5EKR2	5V Reg + CAN + 2 LIN
MCZ33903DP3EK	935333199574	MCZ33903DP3EK	3.3V Reg + CAN + 0 LIN
MC33975TEK	935315721574	MC33975TEK	MULTI SW DETECT INTERFAC
MCZ33903DD3EKR2	935333163518	MCZ33903DD3EKR2	3.3V Reg + CAN + 2 LIN
MCZ33903DS3EKR2	935333167518	MCZ33903DS3EKR2	3.3V Reg + CAN + 2 LIN
MCZ33903DP3EKR2	935333199518	MCZ33903DP3EKR2	3.3V Reg + CAN + 0 LIN
MCZ33903DP5EK	935333218574	MCZ33903DP5EK	SBC W/HIGH SPEED CAN 5V
MCZ33903DD3EK	935333163574	MCZ33903DD3EK	3.3V Reg + CAN + 2 LIN
MCZ33903DD5EK	935333165574	MCZ33903DD5EK	5V Reg + CAN + 2 LIN
MCZ33903DS3EK	935333167574	MCZ33903DS3EK	3.3V Reg + CAN + 2 LIN
MCZ33903DS5EK	935333189574	MCZ33903DS5EK	5V Reg + CAN + 2 LIN